### FOR USE AS LAMP, RELAY, OR MOS DRIVERS

#### featuring

- Full Decoding of Input Logic
- 80-mA Sink-Current Capability
- All Outputs Are Off for Invalid BCD Input Conditions

#### **FUNCTION TABLE**

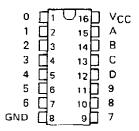
NO.	INPUTS				_	OUTPUTS								
IVO.	D	C	В	Α	0	1	2	3	4	5	6	7	8	9
0	ΓL	L	L	L	L	н	Н	Н	Н	Н	Н	Н	Н	Η
1	L	L	L	Н	н	L	н	Н	Н	Н	Н	Н	Н	Н
2	L	L	Н	L	H	Н	L	Н	H	Н	Н	Н	Н	н
3	L	L	Н	Н	H	Н	Н	L	Н	Η	Н	Н	Н	н
4	L	Н	L	L	н	Н	Н	Н	L	Н	Н	Н	Н	H
5	L	Н	L	Н	Н	Н	Н	Н	Н	Ł	Н	Н	Н	н
6	L	Н	Н	L	н	Н	H	Н	Н	Н	L	H	Н	н
7	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	Ł	H	Н
8	Н	L	L	L.	н	Н	Н	Н	Н	Н	Н	Н	L	н
9	Н	Ļ,	L	Н	н	Н	Н	Н	H	H	Н	Н	Н	L
	Н	L	Н	٦	Н	Н	H	Н	Н	Н	H	Н	Н	Н
l □	Н	L	H	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	н
A L	Н	Н	L	L	Н	Η	Н	Н	Н	Н	Н	Н	H	н
INVALID	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	H
] = ;	Н	Н	Н	L	Н	Н	Н	Н	Н	H	Н	Н	Н	н
	Н	Н	н	Н	Н	Н	Н	Н	Н	Н	н	Н	Н	н

H = high level (off), L = low level (on)

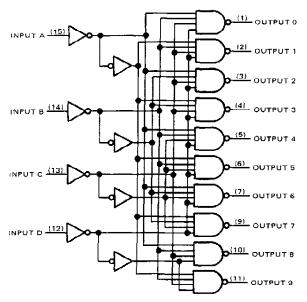
### description

These monolithic BCD to decimal decoders/drivers consist of eight inverters and ten four-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid BCD input logic ensures that all outputs remain off for all invalid binary input conditions. These decoders feature TTL inputs and highperformance, n-p-n output transistors designed for use as indicator/relay drivers or as open-collector logiccircuit drivers. Each of the high-breakdown output transistors (30 volts) will sink up to 80 milliamperes of current. Each input is one normalized Series 54/74 load. Inputs and outputs are entirely compatible for use with TTL logic circuits, and the outputs are compatible for interfacing with most MOS integrated circuits. Power dissipation is typically 215 milliwatts.

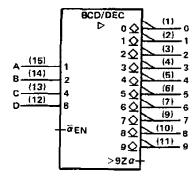
### SN5445 . . . J OR W PACKAGE SN7445 . . . N PACKAGE (TOP VIEW)



## logic diagram (positive logic)



### logic symbol



Pin numbers shown are for J, N, and W packages.

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note I)		 7 V
Input voltage		 5.5 V
Maximum current into any output (off-state)	· ·	
Operating free-air temperature range: SN5445 Circu		 -55°C to 125°C
SN7445 Circu	<b>;</b>	 . 0°C to 70°C
Storage temperature range		 -65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN544	5	SN7445			LINIT
	MIN	NOM	MAX	MIN	MOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage			30			30	٧
Operating free-air temperature, T <sub>A</sub>	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

L	PARAMETER	TEST CONDITIONS†			TYP‡	MAX	UNIT
ViH	High-level input voltage			2			٧
VIL	Low-level input voltage					8.0	V
Vik	Input clamp voltage	VCC = MIN, II = -12 mA				-1.5	V
VO(on)		VCC = MIN, VtH = 2 V,	I <sub>O(on)</sub> = 80 mA		0.5	0.9	v
	On-state output voltage	V1L = 0.8 V	IO(on) = 20 mA			0.4	] V
<sup>1</sup> O(off)	Off-state output current	VCC = MIN, VIH = 2 V,				250	μА
	Offisiate Output carroin	$V_{1} = 0.8 \text{ V}, V_{O\{off\}} = 30 \text{ V}$				230	μ.Α.
11	Input current at maximum input voltage	VCC = MAX, VI ≈ 5.5 V				1	mΑ
Ίμ	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V				40	μА
TIL.	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V				-1.6	mA
1	C	V MAY C- N 2	SN5445		43	62	^
Icc	Supply current	VCC - MAX, See Note 2	SN 7445		43	70	mA

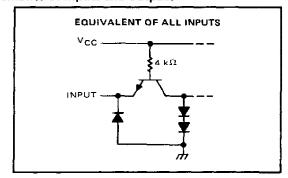
<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.  $\ddagger$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

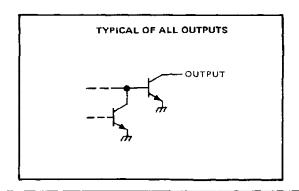
# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

L	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
TPLH	Propagation delay time, low-to-high-level output	C <sub>1</sub> = 15 pF, R <sub>1</sub> = 100 Ω, See Note 3			50	ns
tPHL.	Propagation delay time, high-to-low-level output	C[ - 15 pr, n[ - 100 11, See Note 3			50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

# schematics of inputs and outputs





NOTE 2:  ${}^{1}_{\mbox{\scriptsize CC}}$  is measured with all inputs grounded and outputs open.

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